MISSION COMPUTER WITH DUAL REMOVABLE DISK





A high-performance rugged mission computer engineered for demanding edge workloads and multimedia applications. Featuring a fanless design and equipped with powerful Intel® Xeon® processors, multiple display outputs, and extensive I/O options, designed to meet the rigorous requirements of military and aerospace environments.

The mission computer is designed to deliver exceptional computing power with support for Intel® Xeon® processors, making it ideal for demanding mission-critical applications.

It supports up to 64GB of DDR4 memory with ECC or non-ECC options to ensure reliable performance and data integrity.

The system offers flexible display capabilities with two HDMI ports and one VGA output, enabling three independent and simultaneous video streams.

It also provides a wide range of I/O interfaces including multiple Gigabit Ethernet ports, USB 2.0 and 3.0, programmable serial ports, audio connections, and PS/2.

Storage is secure and versatile, featuring dual removable 2.5" SATA SSDs with secure erase, a removable CFast card, and an internal mSATA slot.

Built to withstand harsh environments, it complies with MIL-STD-810G and RTCA/DO-160G standards for shock, vibration, and extreme temperatures.

Power protection features are integrated to meet MIL-STD-704F, including safeguards against over-voltage, over-current, and transient power disruptions.

The I/O connectors and the power supply input can be provided with MIL-GRADE connectors upon request.

FEATURES

- Supports 11th Gen Intel® Xeon®
 W-11865MRE or 9th Gen Intel® Xeon®
 E-2276ML processors
- Memory: Up to 64GB DDR4
- Secure storage, featuring dual removable 2.5" SATA SSDs
- Flexible display capabilities
- Fanless design with no external airflow prescriptions
- Internal MiniPCI Express slot is available for further expansion
- MIL-STD-810G compliant



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TECHNICAL SPECIFICATIONS

SYSTEM	
CPU Options	9th Gen Intel® Xeon® E-2276ML, 2.0/4.2GHz, 12MB, 6C/12T
	11th Gen Intel® Xeon® W-11865MRE 2.60 GHz, 24MB, 8C/16T
Memory	2x 16GB Dual channel 2133/2400 MHz DDR4 memory in dual SODIMM sockets;
	ECC / non ECC support (9th Gen)
	2x 32GB Dual channel 2933MT/s DDR4 memory; ECC / non ECC support (11th Gen)
Ethernet	1x 10/100/1000 GbE LAN interface with I219 controller
	3x 10/100/1000 GbE LAN interfaces with I210 controller
Storage	1x mSATA slot
	2x removable 2.5" SATA SSD with secure erase option
	1x removable CFast card
Serial	4x programmable serial ports RS232/RS422/RS485
Front I/O	4 x USB 3.2, 1 x DP, 1x HDMI, 2 x 2.5GbE RJ45.
Video outputs	3 independent and simultaneous displays (2x HDMI, 1x VGA)
Audio	Intel® HD Audio integrated in chipset
Software	Windows 11, Windows 10, Linux 64-bit
POWER SUPPLY	
Power Supply	15-36VDC Single Power Supply

MECHANICAL

Dimensions	256mm x 203 mm x 116 mm (W x D x H)
Weight	5.3 kg
Cooling	Fanless design, no external forced airflow is required
Interfaces	3x MIL-DTL-38999 Military circular connectors 2x USB 3.0 Quick Lock USB 3.0 Micro-D connectors 2x HDMI (with mating retention via custom backshell)

ENVIRONMENTAL - (DESIGN TO MEET)

Operating Temperature	Standard: -45 C / $+70$ C Extended: -20 C / $+55$ C (depending on the configurations)
Operating Humidity	5% to 95% non-condensed (depending on the configurations)
Storage Temperature	-40C / +85 C (depending on the configurations)
Vibrations	MIL-STD-810G, Method 514.7, Cat 4 - Proc. I - 2.24 Grms, 5-500 Hz 60 min/axis for 3 axes
Altitude	Max 25.000 feet
Operating Shock	MIL-STD-810G Proc. I Method 516.7 - 15g / 11ms – half sine
Transport shock	MIL-STD-810G Proc. II Method 516.7 - 30g / 9ms sawtooth
Certifications	Directive 2014/35/UE-LVD / Directive 2014/30/UE-EMC Directive 2011/65/UE - RoHS / Regulation (EC) No 1907/2006 - REACH

Servers and workstations are designed in accordance with the environmental specifications indicated. Some parameters depend on the configuration. Equipment may be subjected to dedicated test profiles.

